



Study of optical and transport properties of nitrogen doped titanium dioxide thin films

R. Ramos, D. Scoca, F. Alvarez, L. F. Zagonel

Instituto de Física "Gleb Wataghin"
Universidade Estadual de Campinas – Unicamp, 13083-859,
Campinas, São Paulo, Brasil

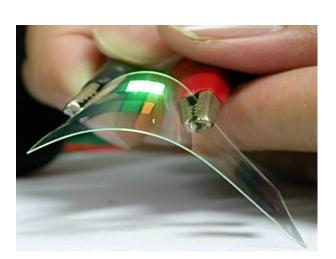


Introduction

Transparent Conducting Electrodes are part of many technological devices.







Each application has is own challenges and demands.



Properties of common TCO

	AZO	ITO	FTO	TNO (Nb:TiO ₂)
Resistivity (Ωcm)	2-3.10-4	1-2.10-4	8.10-4	9. 10-4
Bandgap (eV)	3,3	3,7	3,7	3,4
Light Transmission (%)	85	85	80	75
Cost	Low	High	Low	Low
Stability	3°	2°	1°	?

TiO₂ is interesting because it is not toxic, has high chemical stability, high corrosion resistance, is cheap and many growth routes are well stablished.

- T. Minami, Semicond. Sci. Technol., 20 (2005), pp. S35–S44
- A. Muthukumar et. al., Thin Solid Films 545 (2013), 302-309
- N. Yamada et. al., Thin Solid Films 516 (2008), 5754-5757
- H. Lemire et. al., Proceedings of SPIE (2013), 882502
- T. Minami el. al., Journal of Vacuum Science & Technology A 17 (1999), 1822



Doping TiO₂

	Nb:TiO ₂	Ta:TiO ₂	W:TiO ₂	N:TiO ₂
Resistivity (Ωcm)	9. 10-4	2,5.10-4	2.10^{-3}	2.10-1
Visible Light Transmission (%)	75	95	90	65

Anion doping with **Nitrogen** is interesting, but results are behind others.

This poor performance of N:TiO₂ may be due to problems to control the crystallinity of TiO₂ film under doping by reactive sputtering.

- N. Yamada et. al., Thin Solid Films 516 (2008), 5754-5757
- T. Hitosugi et. al., Japanese Journal of Applied Physics, 44 (2005), pp L1063-L1065
- U. Takeuchi et. al., Journal of Applied Physics, 107 (2010), 023705
- H. Akazawa, Japanese Journal of Applied Physics, 49 (2010), 080215T



Objective

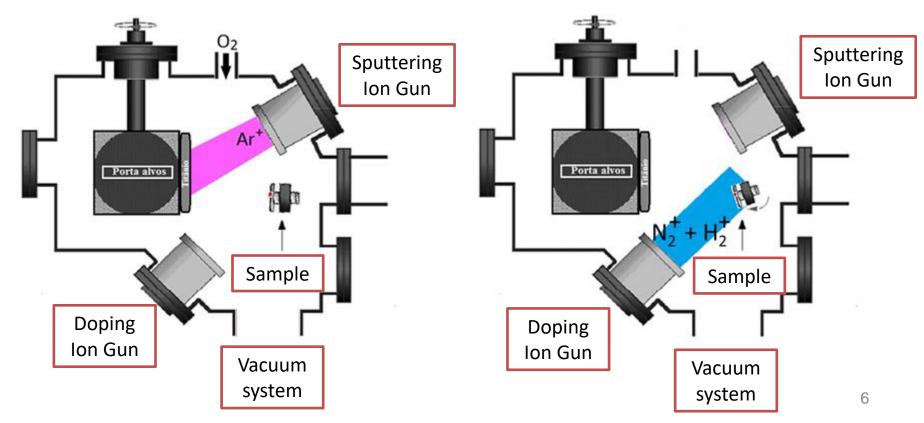
Here, we have grown *undoped* (*in principle* stoichiometric) Anatase TiO₂ thin films by reactive sputtering. In a second step, the films were doped by low energy ion implantation and inward thermal diffusion.



Growth System

Step 1:
Deposition of Anatase TiO₂
by Ti target sputtering under
O₂ atmosphere.

Step 2: Doping by 400eV N+ and H+ ions.





Sample preparation settings

Growth parameters

Fixed settings for all samples			
P_{O_2}	25 mPa		
P_{Ar}	10 mPa		
Ar ⁺ Current density	8 mA/cm²		
Ar^+ beam energy	1500 eV		
Deposition time	50 min		

Setting changed among samples			
Deposition temperature	400, 500 [°C]		

Doping parameters

Fixed settings for all samples		Setting changed among samples		
P_{N_2}	21 mPa	Deposition and doping temperature	400, 500 [°C]	
P_{H_2}	2,1 mPa		0, 10, 30, 60 [min]	
Current density $N_2^+ + H_2^+$	1,2 mA/cm²	Doping time		

150 eV

Vacuum base pressure: 0,2 mPa

Leading to film thickness of about 85 nm.

Beam energy

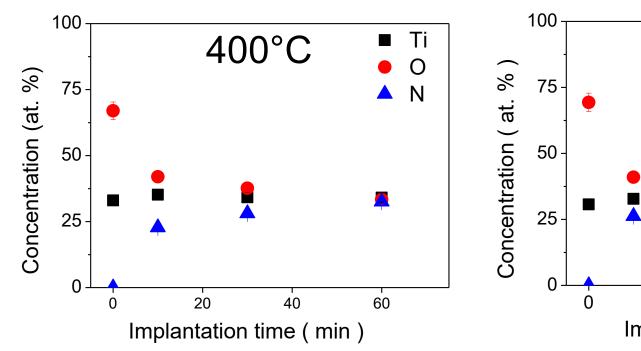
 $N_2^+ + H_2^+$

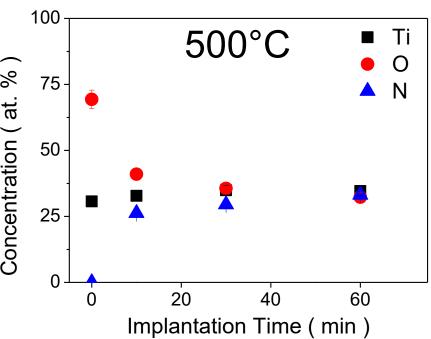
Deposited on amorphous quartz substrate.



Surface Composition

Determined by in situ XPS.

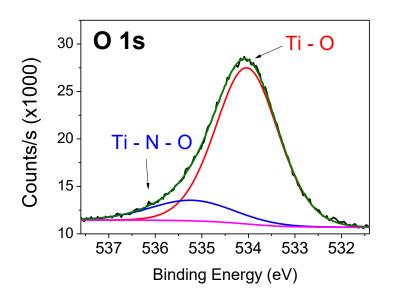


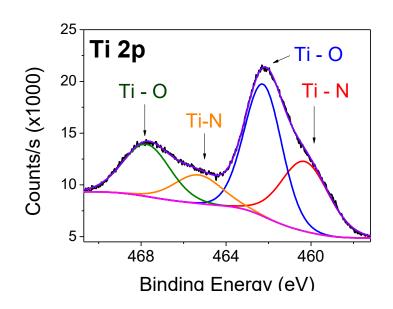


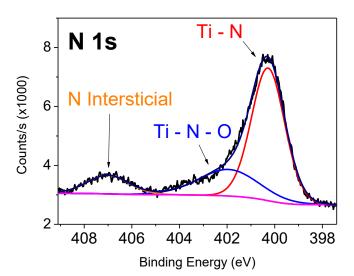
For both growth and doping temperatures, **nitrogen** concentration increase in the surface up to about 30 at. % while **oxygen** concentration decreases.



Chemical States





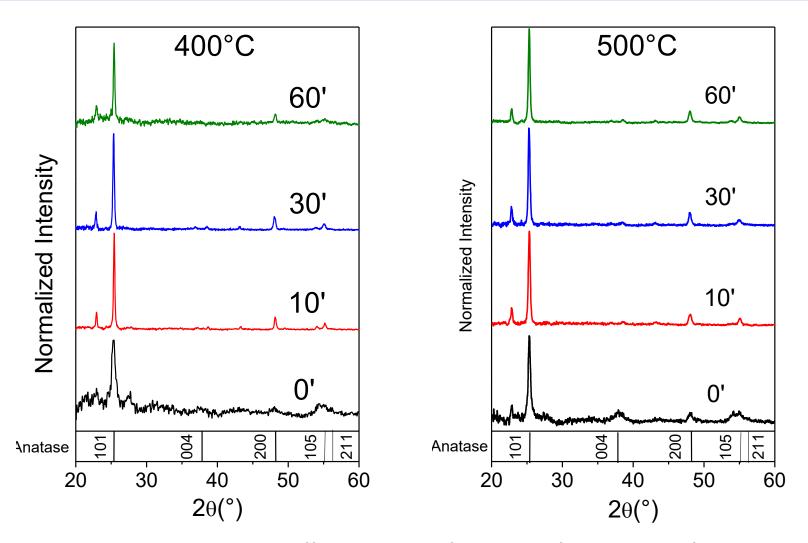


In situ XPS confirms the formation of chemical bonding among Ti, O and N.

Ti 2p has TiN-like components, but the surface is not pure TiN.



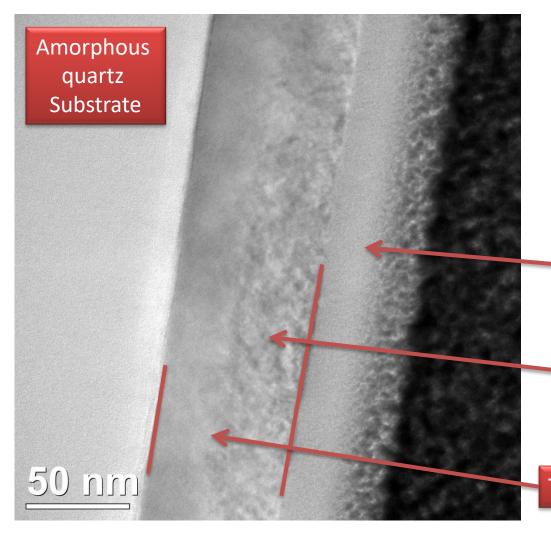
Crystal structure



Grazing incidence X-ray Diffraction confirms the formation of Anatase that indicates that this phase is preserved after doping (ion implantation).



Thin film morphology



N:TiO₂ TEM cross-section.

Sample: 500°C – 60 minutes.

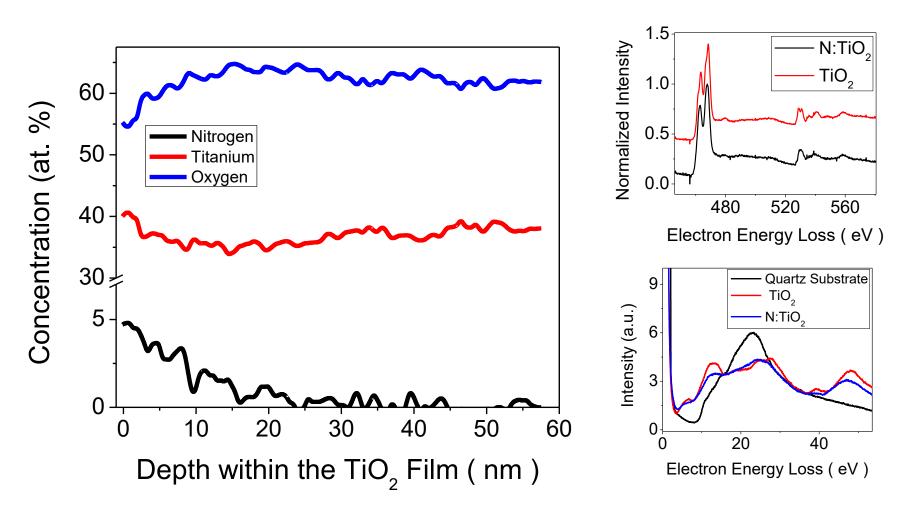
Protection for FIB sample preparation

N doped region

TiO₂ thin film



Depth profiles

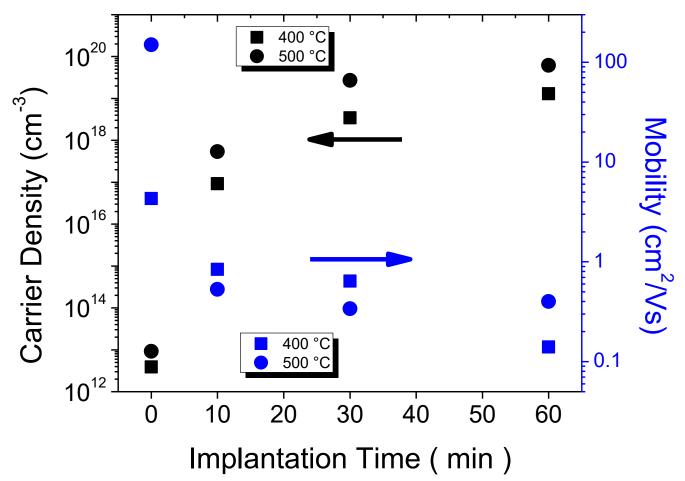


Electron Energy Loss (EELS) profiles indicate that Nitrogen diffuses at least up to ~20 nm. The dielectric function and Ti and O edges indicate changes down to ~30 nm.



Electrical properties I

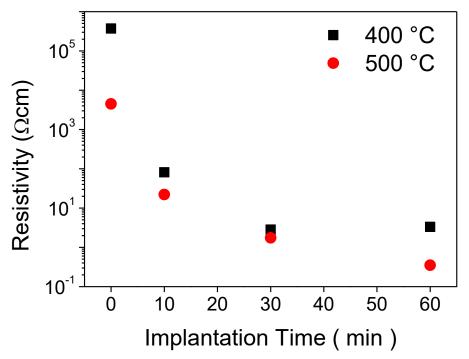
Carrier density up to $\sim 6 \times 10^{19} \text{ cm}^{-3}$. Mobility fell to $\sim 0.5 \text{ cm}^2/\text{Vs}$ (for $500^{\circ}\text{C} - 60' \text{ sample}$). (Typical ITO values are 10^{21}cm^{-3} and $20 \text{ cm}^2/\text{Vs}$).





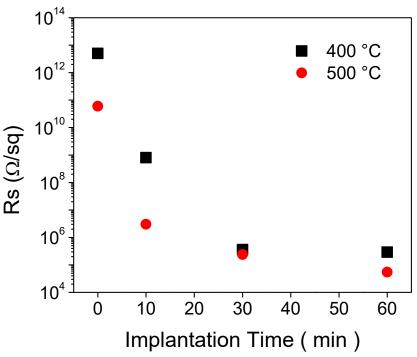
Electrical properties II

Resistivity down to ~3 $10^{-1} \Omega$ cm. (ITO resistivity ~1 $10^{-4} \Omega$ cm) (for 500° C – 60° sample).



Hall Measurements with indium contacts.

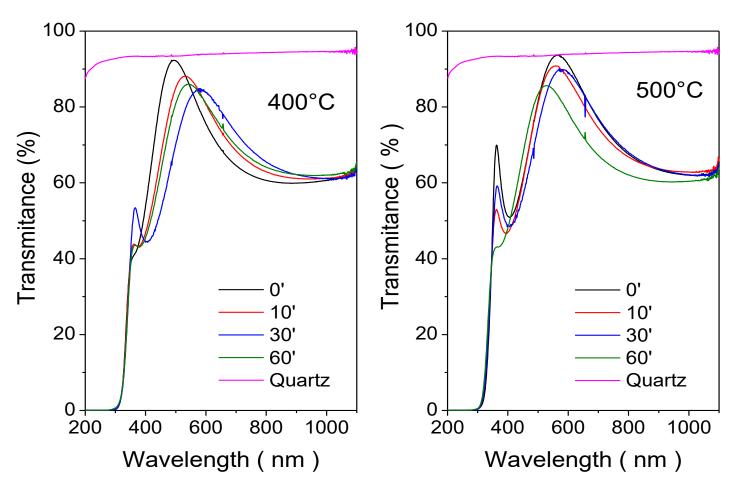
Agrees well with Hall resistivity. Sheet resistance down to 55 k Ω . (for 500°C – 60' sample).



4-probe electrical measurements



Light transmission

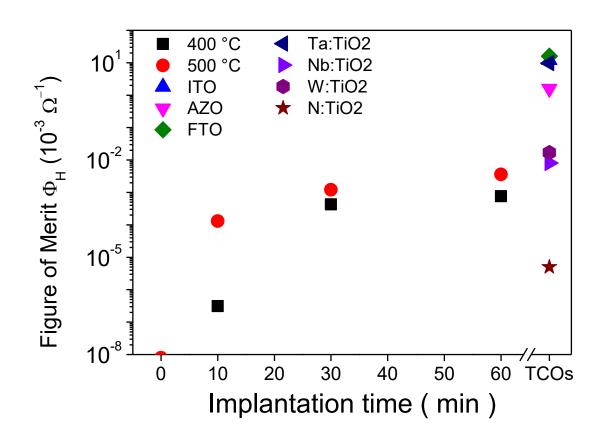


Bandgap: from 3.1 eV to 3.3 eV

Total transmission in the visible (measured by CCD spectrometer). Transmittance between 80 and 90% at 550 nm. Interference fringes are observed.



Figure of Merit



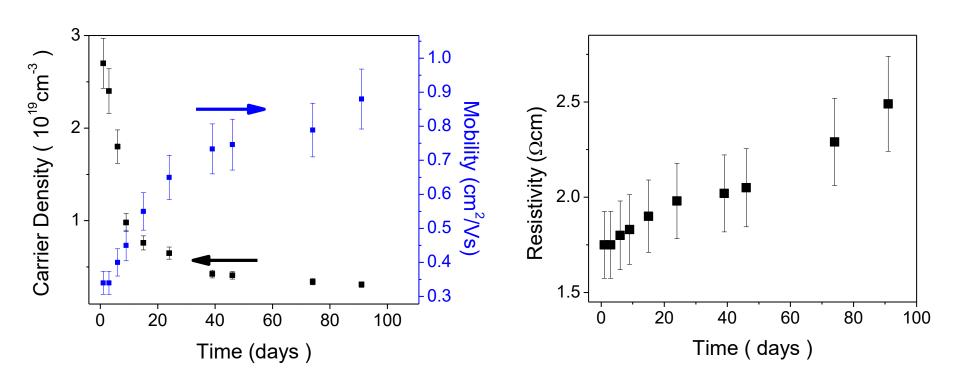
$$\Phi_H = \frac{T^{10}}{R_S} = e^{-10\alpha d} \sigma d$$

Figure of Merit is similar to some good literature results.



Stability

Shelf stability for the 500°C – 30 minutes sample.



Low but significant changes in Mobility, Carrier density and Resistivity are observed. Resistivity increased by ~40%.

Sample was **not** covered or protected by any passivation layer.



Concluding remarks

- Low energy (400eV) ion implantation with N⁺ ions is effective for TiO₂ doping.
- Nitrogen diffusion reached ~30 nm (1/3 of the TiO₂ film).
- Anatase phase is not significantly affected by doping up to ~6 10¹⁹ cm⁻³.
- Resistivity as low as $\sim 3 \cdot 10^{-1} \Omega \text{cm}$ was obtained.
- We can speculate that longer nitriding times could lead to deeper diffusion, higher doping and lower resistivity.



Acknowledgments







Thank you for kind your attention.